



Material Content Data Sheet



Sales Product Name		BSO207P H		Issued		1. August 2018		
MA#		MA000719842						
Package		PG-DSO-8-40		Weight*		82.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.616	1.96	1.96	19565	19565
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		119	
	non noble metal	zinc	7440-66-6	0.039	0.05		475	
	non noble metal	iron	7439-89-6	0.785	0.95		9503	
wire	non noble metal	copper	7440-50-8	31.880	38.59	39.60	385860	395957
	non noble metal	copper	7440-50-8	0.275	0.33	0.33	3334	3334
	encapsulation	organic material	carbon black	1333-86-4	0.232	0.28		2811
encapsulation	plastics	epoxy resin	-	7.199	8.71		87130	
	inorganic material	silicondioxide	60676-86-0	39.013	47.22	56.21	472188	562129
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9850	9850
plating	noble metal	silver	7440-22-4	0.063	0.08	0.08	761	761
glue	plastics	epoxy resin	-	0.104	0.13		1261	
	noble metal	silver	7440-22-4	0.590	0.71	0.84	7143	8404
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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